

PRODUCT DATA SHEET

# Flip-Chip Flux NC-26-A

## Features

- Designed for flip-chip dipping applications
- Tackiness suitable for holding die during assembly
- Bubble-free airless packaging
- Ultra-low residue
- Halogen-free
- No-clean

## Introduction

**Flip-Chip Flux NC-26-A** is a halogen-free, no-clean flip-chip dipping flux which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

## Properties

Property	Value	Test Method
Flux Type	RELO	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light Tan	Visual
Typical Viscosity	4kcps	Brookfield DV-1. 51CPE Spindle @10rpm after 5 mins
Typical Tack Strength	200 g/cm <sup>2</sup>	J-STD-005 (IPC-TM-650: 2.4.44)
Typical Acid Value	36mg KOH/g	Titration
SIR (ohms)	Pass	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Post Reflow Residual Weight	~5%	TGA Data
Working Life	≥ 8 hr	Customer Experience (Dipping)
Shelf Life	6 months when stored at 0 to 30°C	Viscosity Change/ Microscope Examination

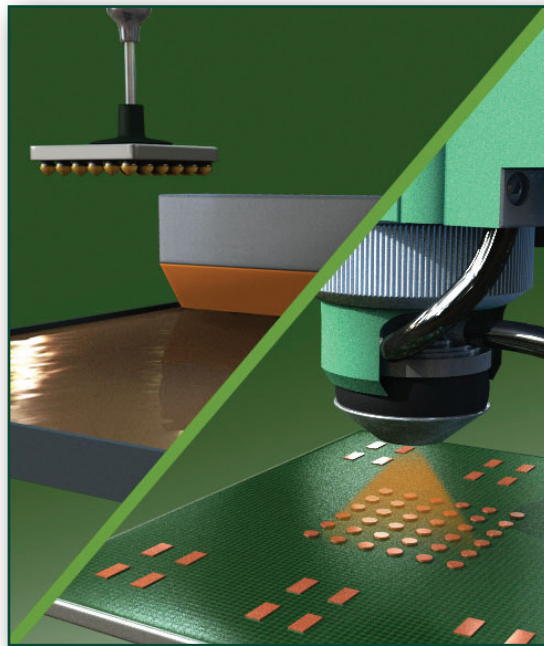
All information is for reference only. Not to be used as incoming product specifications.

## Application

**Flip-Chip Flux NC-26-A** will have strong adhesion to epoxy-based underfill materials, especially epoxy-amine and epoxy-acid based chemistries. **Flip-Chip Flux NC-26-A** should also be suitable for use with many epoxy-anhydride systems.

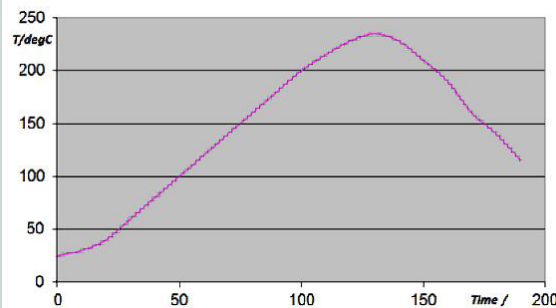
## Cleaning

**Flip-Chip Flux NC-26-A** is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.



## Reflow

### Recommended Profile:



**Flip-Chip Flux NC-26-A** is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **Flip-Chip Flux NC-26-A** can be used on many surface finishes including immersion Ag, Cu, and AuNi. These surfaces can be soldered with SnPb or Pb-free alloys, but require nitrogen if reflow temperatures exceed 240 °C.

OVER→

Form No. 98835 R2

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## Flip-Chip Flux NC-26-A

### Packaging

**Flip-Chip Flux NC-26-A** is most commonly available in 10–30g syringes. Other packaging can be provided to meet specific requirements.

### Storage

**Flip-Chip Flux NC-26-A** syringes and cartridges should be stored tip down for maximum shelf life. **Flip-Chip Flux NC-26-A** should be allowed to reach ambient temperature before use if stored cold.

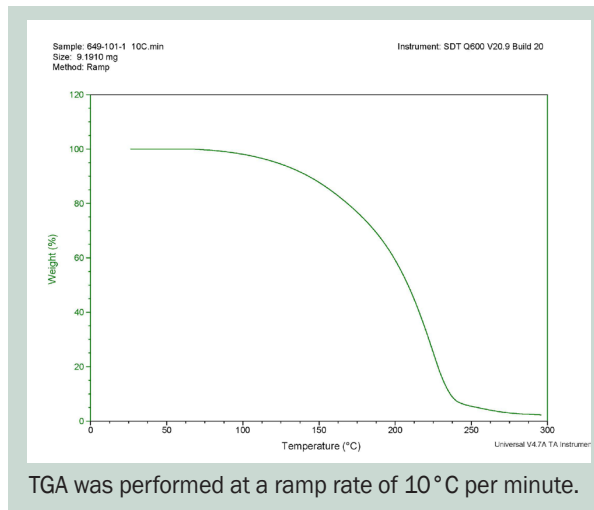
### Technical Support

Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

### Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>

### Thermogravimetric Analysis (TGA)



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